# **General Purpose Transistors**

# **NPN Silicon**

#### **Features**

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage MMBT2222LT1G MMBT2222ALT1G	V <sub>CEO</sub>	30 40	Vdc
Collector - Base Voltage MMBT2222LT1G MMBT2222ALT1G	V <sub>CBO</sub>	60 75	Vdc
Emitter – Base Voltage MMBT2222LT1G MMBT2222ALT1G	V <sub>EBO</sub>	5.0 6.0	Vdc
Collector Current - Continuous	Ic	600	mAdc
Collector Current - Peak (Note 3)	I <sub>CM</sub>	1100	mAdc

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

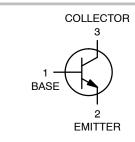
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.
- 3. Reference SOA curve.



# ON Semiconductor®

## http://onsemi.com





SOT-23 **CASE 318** STYLE 6

## **MARKING DIAGRAM**



xxx = 1P or M1BM = Date Code\* = Pb-Free Package

(Note: Microdot may be in either location) \*Date Code orientation and/or overbar may vary depending upon manufacturing location.

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I <sub>C</sub> = 10 mAdc, I <sub>B</sub> = 0) MMBT2222A	MMBT2222	V <sub>(BR)CEO</sub>	30 40		Vdc
Collector – Base Breakdown Voltage ( $I_C = 10 \mu Adc$ , $I_E = 0$ ) MMBT2222A	MMBT2222	V <sub>(BR)CBO</sub>	60 75	- -	Vdc
Emitter – Base Breakdown Voltage ( $I_E$ = 10 $\mu$ Adc, $I_C$ = 0) MMBT2222A	MMBT2222	V <sub>(BR)EBO</sub>	5.0 6.0	- -	Vdc
Collector Cutoff Current (V <sub>CE</sub> = 60 Vdc, V <sub>EB(off)</sub> = 3.0 Vdc)	MMBT2222A	I <sub>CEX</sub>	-	10	nAdc
	MMBT2222 MMBT2222A MMBT2222 MMBT2222A	I <sub>CBO</sub>	- - - -	0.01 0.01 10 10	μAdc
Emitter Cutoff Current ( $V_{EB} = 3.0 \text{ Vdc}$ , $I_{C} = 0$ )	MMBT2222A	I <sub>EBO</sub>	-	100	nAdc
Base Cutoff Current (V <sub>CE</sub> = 60 Vdc, V <sub>EB(off)</sub> = 3.0 Vdc)	MMBT2222A	I <sub>BL</sub>	-	20	nAdc
ON CHARACTERISTICS					
DC Current Gain	MMBT2222A only MMBT2222 MMBT2222A	h <sub>FE</sub>	35 50 75 35 100 50 30 40	- - - 300 - - -	-
Collector – Emitter Saturation Voltage (Note 4) $(I_C = 150 \text{ mAdc}, I_B = 15 \text{ mAdc})$	MMBT2222 MMBT2222A	V <sub>CE(sat)</sub>	- -	0.4 0.3	Vdc
$(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	MMBT2222 MMBT2222A		- -	1.6 1.0	
Base – Emitter Saturation Voltage (Note 4) (I <sub>C</sub> = 150 mAdc, I <sub>B</sub> = 15 mAdc)	MMBT2222 MMBT2222A	V <sub>BE(sat)</sub>	_ 0.6	1.3 1.2	Vdc
$(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	MMBT2222 MMBT2222A		- -	2.6 2.0	
SMALL-SIGNAL CHARACTERISTICS			1	-I	
$\begin{aligned} & \text{Current-Gain - Bandwidth Product (Note 5)} \\ & \text{(I}_{\text{C}} = 20 \text{ mAdc, V}_{\text{CE}} = 20 \text{ Vdc, f} = 100 \text{ MHz)} \end{aligned}$	MMBT2222 MMBT2222A	f <sub>T</sub>	250 300	_ _	MHz
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>obo</sub>	-	8.0	pF
Input Capacitance ( $V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz}$ )	MMBT2222 MMBT2222A	C <sub>ibo</sub>	- -	30 25	pF
Input Impedance $ \begin{aligned} &(I_C=1.0 \text{ mAdc, V}_{CE}=10 \text{ Vdc, f}=1.0 \text{ kHz}) \\ &(I_C=10 \text{ mAdc, V}_{CE}=10 \text{ Vdc, f}=1.0 \text{ kHz}) \end{aligned} $	MMBT2222A MMBT2222A	h <sub>ie</sub>	2.0 0.25	8.0 1.25	kΩ
Voltage Feedback Ratio $ \begin{pmatrix} I_C = 1.0 \text{ mAdc, } V_{CE} = 10 \text{ Vdc, } f = 1.0 \text{ kHz} \end{pmatrix} $ $ \begin{pmatrix} I_C = 10 \text{ mAdc, } V_{CE} = 10 \text{ Vdc, } f = 1.0 \text{ kHz} \end{pmatrix} $	MMBT2222A MMBT2222A	h <sub>re</sub>	- -	8.0 4.0	X 10 <sup>-4</sup>
$\begin{aligned} \text{Small-Signal Current Gain} \\ \text{(I}_{\text{C}} &= 1.0 \text{ mAdc, V}_{\text{CE}} = 10 \text{ Vdc, f} = 1.0 \text{ kHz)} \\ \text{(I}_{\text{C}} &= 10 \text{ mAdc, V}_{\text{CE}} = 10 \text{ Vdc, f} = 1.0 \text{ kHz)} \end{aligned}$	MMBT2222A MMBT2222A	h <sub>fe</sub>	50 75	300 375	-
Output Admittance $ \begin{aligned} &\text{(I}_{C} = 1.0 \text{ mAdc, V}_{CE} = 10 \text{ Vdc, f} = 1.0 \text{ kHz)} \\ &\text{(I}_{C} = 10 \text{ mAdc, V}_{CE} = 10 \text{ Vdc, f} = 1.0 \text{ kHz)} \end{aligned} $	MMBT2222A MMBT2222A	h <sub>oe</sub>	5.0 25	35 200	μmhos

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Charact	Symbol	Min	Max	Unit			
SMALL-SIGNAL CHARACTERISTICS							
Collector Base Time Constant (I <sub>E</sub> = 20 mAdc, V <sub>CB</sub> = 20 Vdc, f = 3	rb, C <sub>c</sub>	_	150	ps			
Noise Figure ( $I_C$ = 100 $\mu$ Adc, $V_{CE}$ = 10 Vdc, $R_S$	NF	-	4.0	dB			
SWITCHING CHARACTERISTICS (MMBT2222A only)							
Delay Time	$(V_{CC} = 30 \text{ Vdc}, V_{BE(off)} = -0.5 \text{ Vdc},$ $I_{C} = 150 \text{ mAdc}, I_{B1} = 15 \text{ mAdc})$	t <sub>d</sub>	=	10	20		
Rise Time	$I_C = 150 \text{ mAdc}, I_{B1} = 15 \text{ mAdc})$	t <sub>r</sub>	-	25	ns		
Storage Time	(V <sub>CC</sub> = 30 Vdc, I <sub>C</sub> = 150 mAdc,	t <sub>s</sub>	_	225	ns		
Fall Time	$I_{B1} = I_{B2} = 15 \text{ mAdc}$	t <sub>f</sub>	-	60	115		

- 4. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.
- 5. f<sub>T</sub> is defined as the frequency at which |h<sub>fe</sub>| extrapolates to unity.

## **SWITCHING TIME EQUIVALENT TEST CIRCUITS**

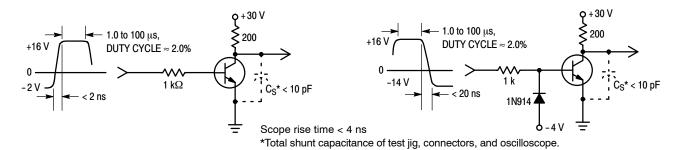


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

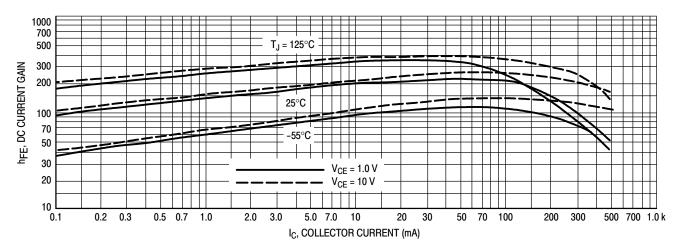


Figure 3. DC Current Gain

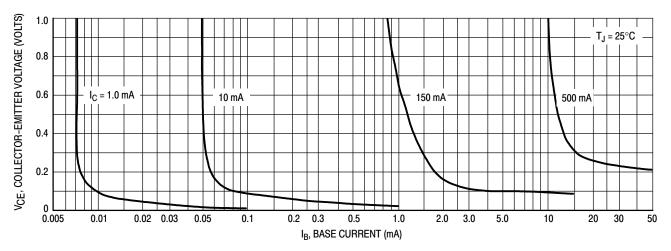


Figure 4. Collector Saturation Region

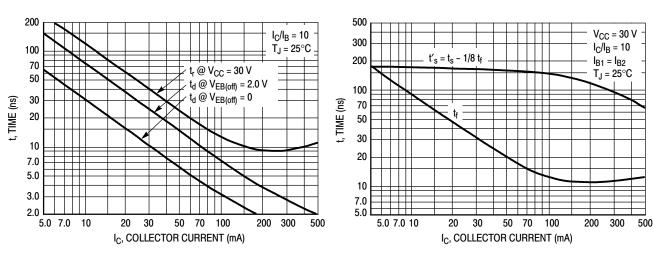


Figure 5. Turn-On Time

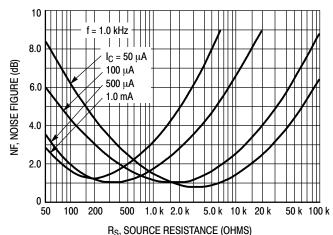


Figure 6. Turn – Off Time

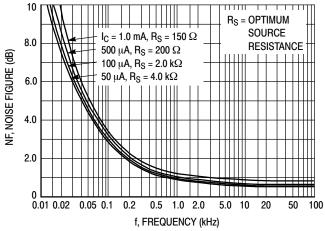
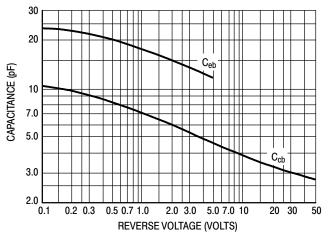


Figure 7. Frequency Effects

Figure 8. Source Resistance Effects



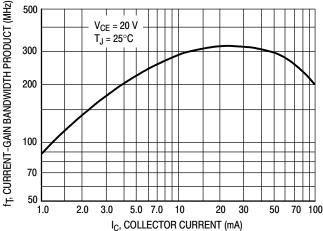
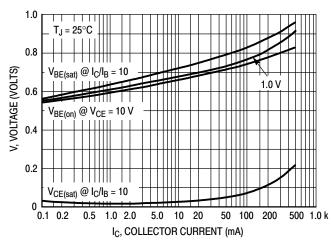


Figure 9. Capacitances

Figure 10. Current-Gain Bandwidth Product



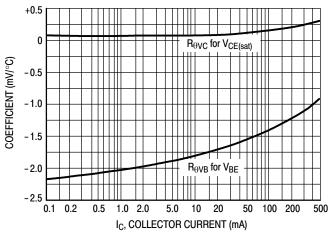


Figure 11. "On" Voltages

Figure 12. Temperature Coefficients

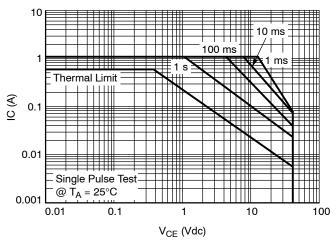


Figure 13. Safe Operating Area

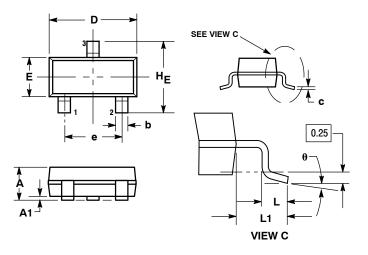
# **ORDERING INFORMATION**

Device	Specific Marking Code	Package	Shipping <sup>†</sup>		
MMBT2222LT1G	M1B	SOT-23 (Pb-Free)	3000 / Tape & Reel		
MMBT2222ALT1G	1P	SOT-23 (Pb-Free)	3000 / Tape & Reel		
MMBT2222LT3G	M1B	SOT-23 (Pb-Free)	10,000 / Tape & Reel		
MMBT2222ALT3G	1P	SOT-23 (Pb-Free)	10,000 / Tape & Reel		

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AN



NOTES:

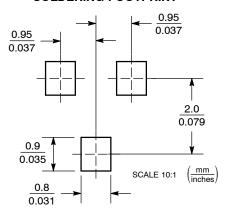
- DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
- 2. GONTHOLLING DIMINION. MOTE
  3. MAXIMUM LEAD THICKNESS INCLUDES
  LEAD FINISH THICKNESS. MINIMUM LEAD
  THICKNESS IS THE MINIMUM THICKNESS OF
  BASE MATERIAL
- BASE MATERIAL.
  4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
C	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6: PIN 1. BASE

- 2. EMITTER
- 3. COLLECTOR

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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